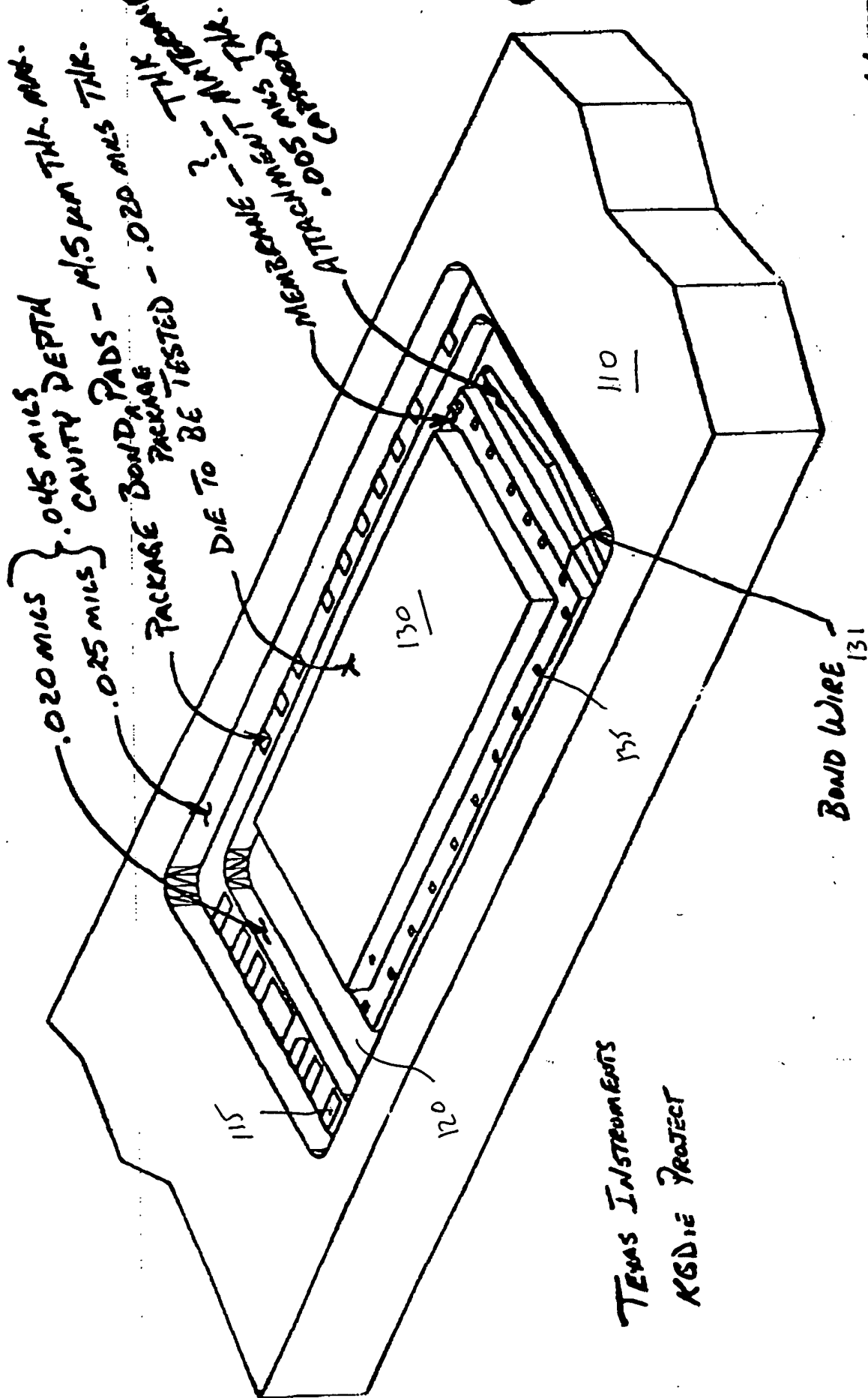


Figure 2 Flip Configuration of K6DIE Package, Exploded View



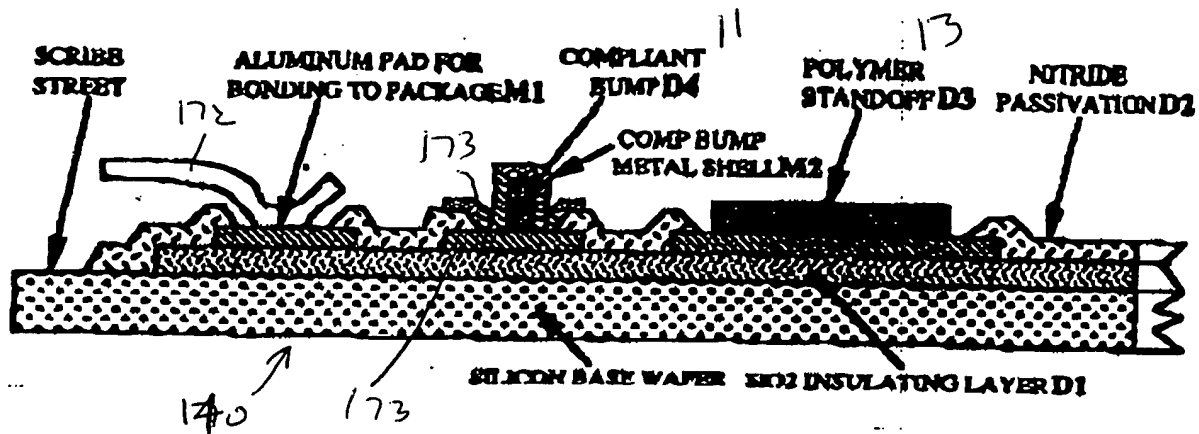
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K6DIE PROJECT

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Figure 3 Compliant bump with polymer standoff on KGD/IL silicon membrane, Cross Section.



⑬

**MILITARY PRODUCTS DIVISION**

## PRODUCTION BY USE OF EXISTING BURN-IN AND TEST TOOLING

- **MULTI BOND LAYER PACKAGE**
- **SINGLE ALIGNMENT PROCESS**
- **REUSABLE**
- **SAME COST AS OF ORIGINAL CONFIGURATION**

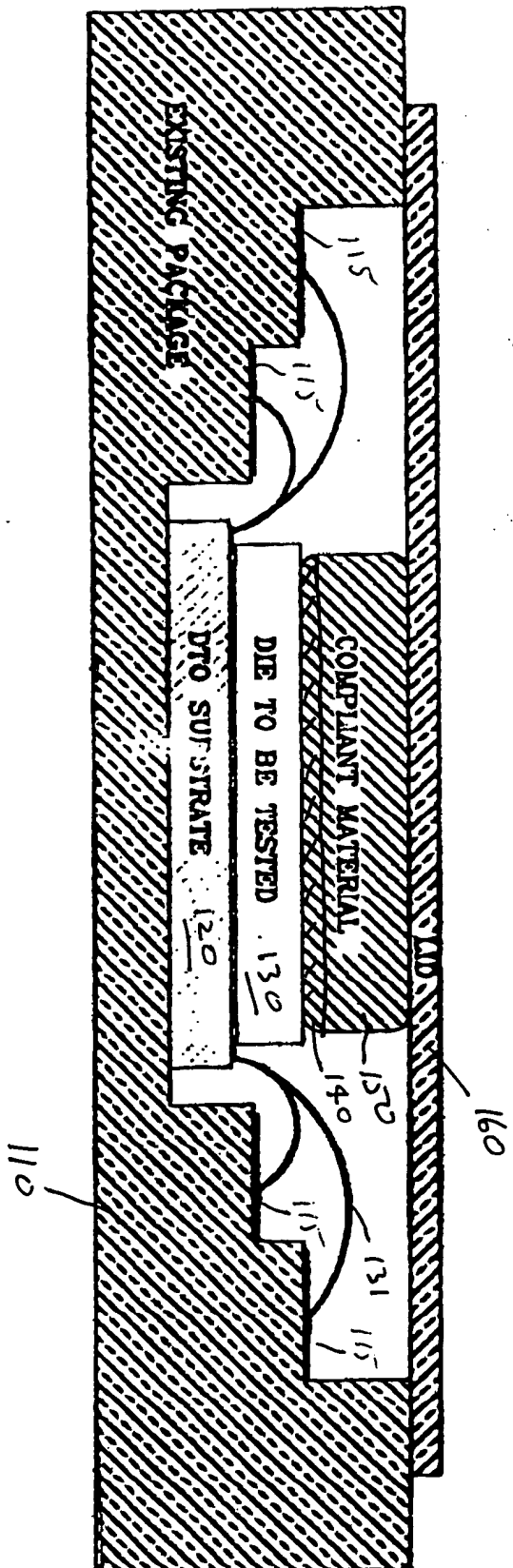


FIGURE 1: Generic KGD/IE Implementation, Exploded view

140. Interconnecting Medium (Inverted View)

171. Inner connection  
172. Outer connection  
173. Conductive Path

Fig. 1b

Fig. 1a

160. Package Lid  
150. Upper Compliant Material  
140. Interconnecting Medium  
(oriented for assembly)  
130. Semiconductor Die  
135. Bond Pads  
120. Lower Compliant Material

110. Standard IC Package  
115. Package Terminals

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